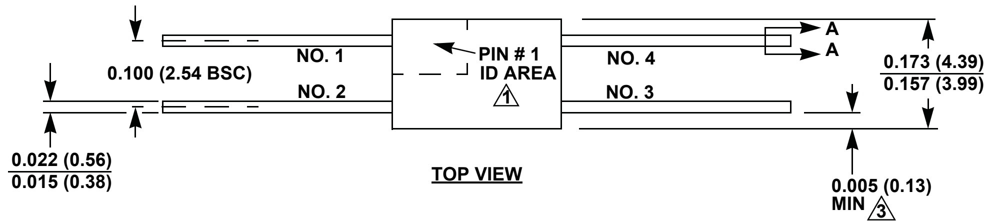
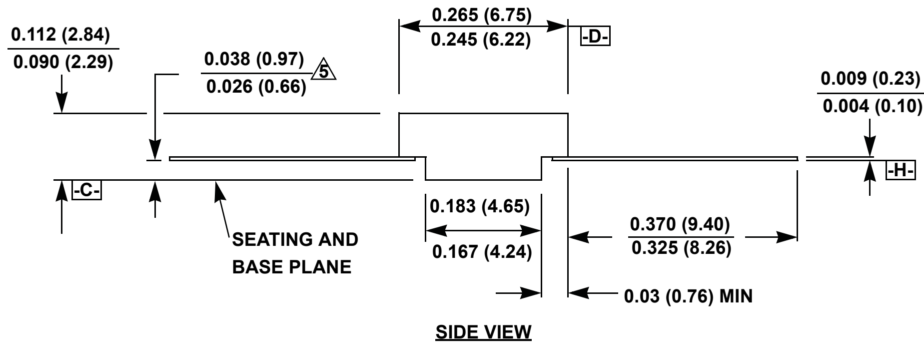
Package Outline Drawing

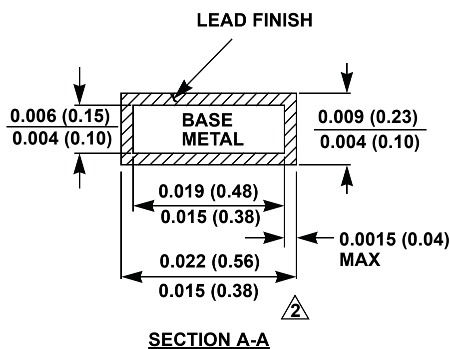
K4.A

4 LEAD CERAMIC METAL SEAL FLATPACK PACKAGE (100 mil LEAD PITCH)
Rev 0, 3/17





BOTTOM VIEW



NOTES:

1. Index area: A notch or a pin 1 identification mark shall be located adjacent to pin 1 and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin 1 identification mark.
2. The maximum limits of lead dimensions (Section A-A) shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. Measure dimension at all four corners.
4. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
5. Dimension shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension minimum shall be reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.
6. The bottom of the package is a ceramic surface.
7. Dimensioning and tolerancing per ASME Y14.5M-1994.
8. Dimensions: INCH (mm), Controlling dimension: INCH.